

TF260L-VB Datasheet N-Channel 60 V (D-S) MOSFET

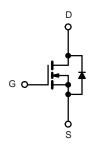
PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a		
60	0.003 at V _{GS} = 10 V	210		
00	0.005 at V _{GS} = 4.5 V	185		

FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unless othe	rwise noted)			
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		210		
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C	- I _D	185 ^a		
Pulsed Drain Current		I _{DM}	200	А	
Continuous Source Current (Diode Conduction)		۱ _S	180 ^a		
Avalanche Current		I _{AS}	70		
Single Avalanche Energy (Duty Cycle \leq 1 %)	L = 0.1 mH	E _{AS}	125	mJ	
Maximum Dawar Dissinction	T _C = 25 °C	Р	136	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	3 ^b , 8.3 ^{b, c}	VV	
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manifestina ta Anti-ada	t ≤ 10 sec	R _{thJA}	15	18	°C/W
Maximum Junction-to-Ambient ^a	Steady State		40	50	
Maximum Junction-to-Case		R _{thJC}	0.85	1.1	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. $t \le 10$ s.

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Parameter Static Drain-Source Breakdown Voltage Gate Threshold Voltage Gate-Body Leakage Zero Gate Voltage Drain Current On-State Drain Current ^b	Symbol V _{DS} V _{GS(th)} I _{GSS} I _{DSS} I _{D(on)}	Test Conditions $V_{GS} = 0 \text{ V}, \text{ I}_D = 250 \mu\text{A}$ $V_{DS} = V_{GS}, \text{ I}_D = 250 \mu\text{A}$ $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 V$ $V_{DS} = 60 V, V_{GS} = 0 V$ $V_{DS} = 60 V, V_{GS} = 0 V$ $V_{DS} = 60 V, V_{GS} = 0 V, T_J = 125 ^{\circ}\text{C}$ $V_{DS} = 60 V, V_{GS} = 0 V, T_J = 175 ^{\circ}\text{C}$ $V_{DS} = 5 V, V_{GS} = 10 V$	Min. 60 1	Typ.a 2 1 2	Max. 3 ± 100 1 50	Unit V nA
Drain-Source Breakdown Voltage Gate Threshold Voltage Gate-Body Leakage Zero Gate Voltage Drain Current	V _{GS(th)} I _{GSS} I _{DSS}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$ $V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 125 \ ^{\circ}C$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 175 \ ^{\circ}C$	1	2	± 100	nA
Gate Threshold Voltage Gate-Body Leakage Zero Gate Voltage Drain Current	V _{GS(th)} I _{GSS} I _{DSS}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$ $V_{DS} = 0 \ V, V_{GS} = \pm 20 \ V$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 125 \ ^{\circ}C$ $V_{DS} = 60 \ V, V_{GS} = 0 \ V, T_J = 175 \ ^{\circ}C$	1	2	± 100	nA
Gate-Body Leakage	I _{GSS} I _{DSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$ $V_{DS} = 60 V, V_{GS} = 0 V$ $V_{DS} = 60 V, V_{GS} = 0 V, T_{J} = 125 °C$ $V_{DS} = 60 V, V_{GS} = 0 V, T_{J} = 175 °C$			± 100	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 \text{ °C}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 175 \text{ °C}$			1	
-		$V_{DS} = 60 V, V_{GS} = 0 V, T_J = 125 °C$ $V_{DS} = 60 V, V_{GS} = 0 V, T_J = 175 °C$			-	μA
-		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			50	μΑ
On-State Drain Current ^b	I _{D(on)}	50 00				
On-State Drain Current ^D	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V			250	
			60			A
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.003		l
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}, \text{ T}_{J} = 125 \text{ °C}$		0.008		Ω
Drain-Source On-State Resistance		V_{GS} = 10 V, I_{D} = 20 A, T_{J} = 175 °C		0.010		
		V _{GS} = 4.5 V, I _D = 15 A		0.005		l
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		60		S
Dynamic						
Input Capacitance	C _{iss}			2650		
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		470		pF
Reverse Transfer Capacitance	C _{rss}			225		l
Total Gate Charge ^c	Qg			47	70	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_{D} = 50 A		10		nC
Gate-Drain Charge ^c	Q _{gd}			12		l
Turn-On Delay Time ^c	t _{d(on)}			10	20	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V}, \text{ R}_{1} = 0.6 \Omega$		15	25	l
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 2.5 \Omega$		35	50	ns
Fall Time ^c	t _f	v		20	30	l
Source-Drain Diode Ratings and Chara	acteristics (T _C = 25 °C)				
Pulsed Current	I _{SM}				60	А
Diode Forward Voltage	V _{SD}	$I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns

Notes:

a. For design aid only; not subject to production testing.

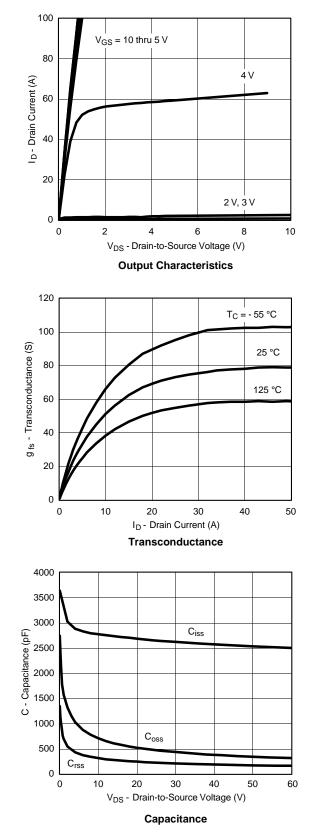
b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

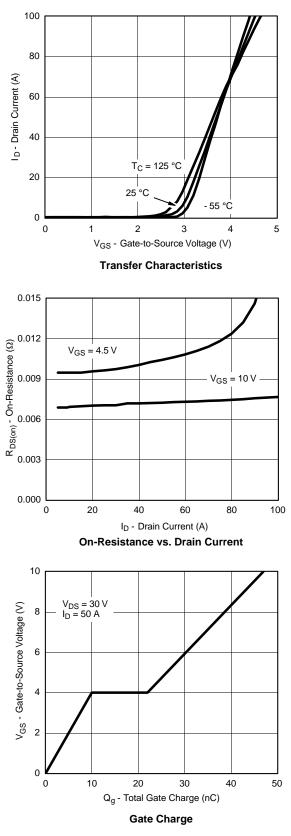
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



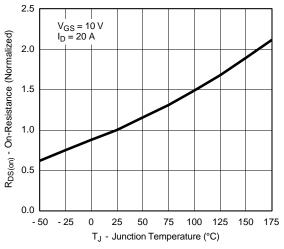




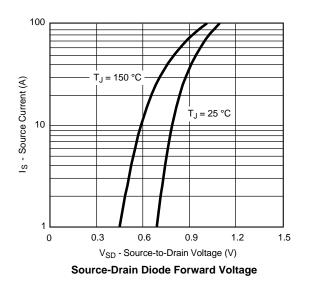




TYPICAL CHARACTERISTICS (25 °C unless noted)

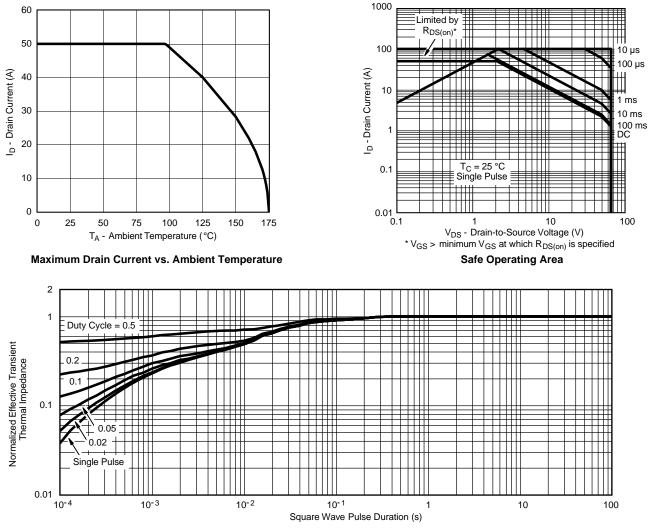


On-Resistance vs. Junction Temperature





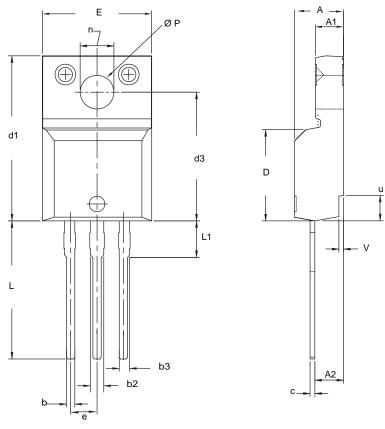
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-220 FULLPAK (HIGH VOLTAGE)



MAX. 4.830 2.830 2.850 0.890 1.400 0.629 9.800 16.120 12.920	MIN. 0.180 0.101 0.099 0.024 0.048 0.048 0.017 0.341 0.622	MAX. 0.190 0.111 0.112 0.035 0.055 0.055 0.025 0.386 0.635	
2.830 2.850 0.890 1.400 0.629 9.800 16.120	0.101 0.099 0.024 0.048 0.048 0.017 0.341 0.622	0.111 0.112 0.035 0.055 0.055 0.025 0.386	
2.850 0.890 1.400 0.629 9.800 16.120	0.099 0.024 0.048 0.048 0.017 0.341 0.622	0.112 0.035 0.055 0.055 0.025 0.386	
0.890 1.400 1.400 0.629 9.800 16.120	0.024 0.048 0.048 0.017 0.341 0.622	0.035 0.055 0.055 0.025 0.386	
1.400 1.400 0.629 9.800 16.120	0.048 0.048 0.017 0.341 0.622	0.055 0.055 0.025 0.386	
1.400 0.629 9.800 16.120	0.048 0.017 0.341 0.622	0.055 0.025 0.386	
0.629 9.800 16.120	0.017 0.341 0.622	0.025 0.386	
9.800 16.120	0.341 0.622	0.386	
16.120	0.622		
		0.635	
12.920	0.404		
	0.484	0.509	
10.630	0.408	0.419	
2.54 BSC	0.100 BSC		
13.730	0.520	0.541	
3.500	0.122	0.138	
6.150	0.238	0.242	
3.450	0.120	0.136	
2.500	0.094	0.098	
0.500	0.016	0.020	
	13.730 3.500 6.150 3.450 2.500	13.730 0.520 3.500 0.122 6.150 0.238 3.450 0.120 2.500 0.094	

Notes

1. To be used only for process drawing. 2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads. 3. All critical dimensions should C meet $C_{pk} > 1.33$. 4. All dimensions include burrs and plating thickness.

5. No chipping or package damage.



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